



CELCON®

Celcon® GB25 acetal copolymer is a 25% glass bead filled grade for low shrinkage and warp resistance in large, flat and thin walled parts.

Chemical abbreviation according to ISO 1043-1: POM

| Product inform | ation |
|----------------|-------|

| Resin Identification Part Marking Code | POM-GB25 >POM-GB25< | | ISO 1043 ISO 11469 |
|---|------------------------|-------------------|------------------------------------|
| Rheological properties | | | |
| Melt volume-flow rate Temperature Load | 13 190 2.16 | | ISO 1133 |
| Melt mass-flow rate Melt mass-flow rate, Temperature | | g/10min | ISO 1133 |
| Melt mass-flow rate, Load Moulding shrinkage, parallel Moulding shrinkage, normal | 2.16 1.5 1.3 | % | ISO 294-4, 2577 ISO 294-4, 2577 |
| | 1.3 | 70 | 130 294-4, 2377 |
| Typical mechanical properties | | | |
| Tensile modulus | | MPa | ISO 527-1/-2 |
| Tensile stress at yield, 50mm/min | | MPa | ISO 527-1/-2 |
| Tensile strain at yield, 50mm/min Flexural modulus | | % MPa | ISO 527-1/-2 ISO 178 |
| Compressive stress at 1% strain | | мРа | ISO 604 |
| Charpy notched impact strength, 23°C | | kJ/m ² | ISO 179/1eA |
| Charpy notched impact strength, -30°C | | kJ/m² | ISO 179/1eA |
| Izod notched impact strength, 23°C | 2.6 | kJ/m² | ISO 180/1A |
| Izod impact strength, -40°C | 3.74 | kJ/m² | ISO 180/1U |
| Poisson's ratio | 0.422 | | |
| Thermal properties | | | |
| Melting temperature, 10°C/min | 165 | | ISO 11357-1/-3 |
| Temperature of deflection under load, 1.8 MPa | 105 | | ISO 75-1/-2 |
| Coefficient of linear thermal expansion (CLTE), parallel | | E-6/K | ISO 11359-1/-2 |
| Coefficient of linear thermal expansion (CLTE), normal | 80 | E-6/K | ISO 11359-1/-2 |
| Flammability | | | |
| Oxygen index | 15.6 | % | ISO 4589-1/-2 |
| Physical/Other properties | | | |
| Humidity absorption, 2mm | 0.2 | % | Sim. to ISO 62 |
| Water absorption, 2mm | 0.65 | | Sim. to ISO 62 |
| Water absorption, Immersion 24h | 0.2 | | Sim. to ISO 62 |
| Density | 1620 | kg/m³ | ISO 1183 |

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Injection

| no | |
|----------|---|
| 100 | °C |
| 3 - 4 | h |
| ≤0.2 | % |
| 190 | °C |
| 180 | °C |
| 200 | °C |
| ≤0.3 | m/s |
| 105 | °C |
| 90 | °C |
| 120 | °C |
| 60 - 120 | MPa |
| 2 | MPa |
| | 100 3 - 4 ≤0.2 190 180 200 ≤0.3 105 90 120 60 - 120 |

Characteristics

Processing Injection Moulding

Delivery form Pellets

Special characteristics Low Warpage

Additional information

Injection molding

Preprocessing

Drying is generally not required because Celcon® and Hostaform® acetal copolymers are not hydroscopic nor are they degraded by moisture during processing. Excessive moisture can lead to splay (silver streaking) in molded parts. For better uniformity in molding especially when using regrind or material that has been stored in containers open to the atmosphere, recommended drying conditions are 80 C (180 F) for 3hours. Desiccant hopper dryers are not required. Maximum water content = 0.35%

Processing

Standard reciprocating screw injection molding machines with a high compression screw (minimum 3:1 and preferably 4:1) and low back pressure (0.35 Mpa/50 PSI) are favored. Using a low compression screw (I.E. general purpose 2:1 compression ratio) can result in unmelted particles and poor melt homogeneity. Using a high back pressure to make up for a low compression ratio may lead to excessive shear heating and deterioration of the material.

Melt Temperature: Preferred range 182-199 C (360-390 F). Melt temperature should never exceed 230 C (450 F).

Mold Surface Temperature: Preferred range 82-93 C (180-200 F) especially with wall thickness less than 1.5 mm (0.060 in.). May require mold temperature as high as 120 C (250 F) to reproduce mold surface or to assure minimal molded in stress. Wall thickness greater than 3mm (1/8 in.) may use a cooler (65 C/150 F)

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mold surface temperature and wall thickness over 6mm (1/4 in.) may use a cold mold surface down to 25 C (80 F). In general, mold surface temperatures lower than 82 C (180 F) may hinder weld line formation and produce a hazy surface or a surface with flow lines, pits and other included defects that can hinder part performance.

Postprocessing

Postprocessing conditioning and moisturizing are not required. It may be necessary to fixture large or complicated parts with varying wall thickness to prevent warpage while cooling to ambient temperature.

Processing Notes

Pre-Drying

Drying is not normally required. If material has come in contact with moisture through improper storage or handling or through regrind use, drying may be necessary to prevent splay and odor problems.

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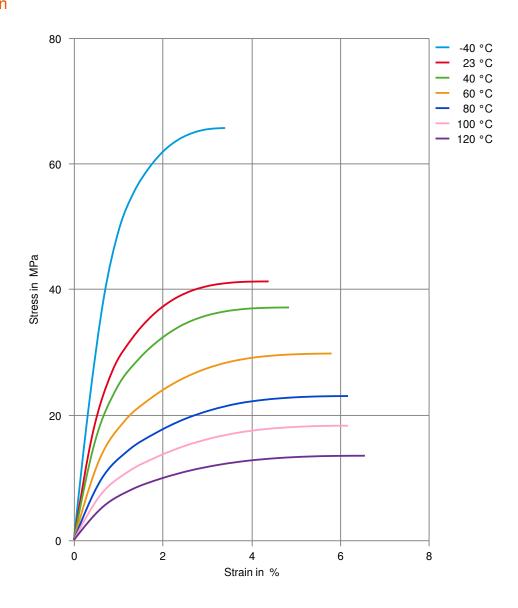
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Stress-strain



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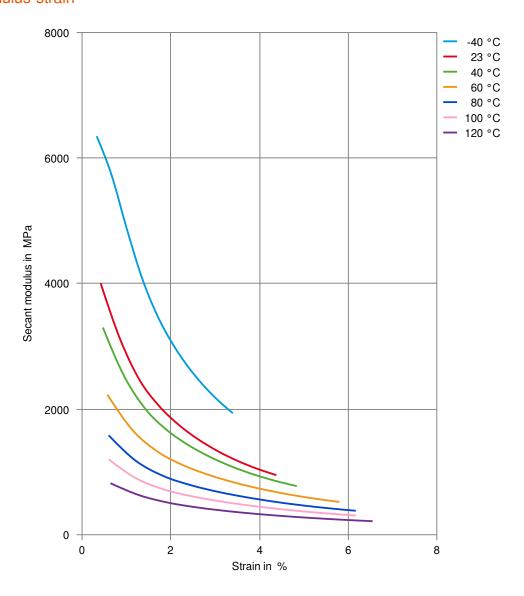
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Secant modulus-strain



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